

EECS 240

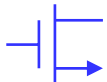
Analog Integrated Circuits

Topic 18: MOS S/H

Ali M. Niknejad and Bernhard E. Boser

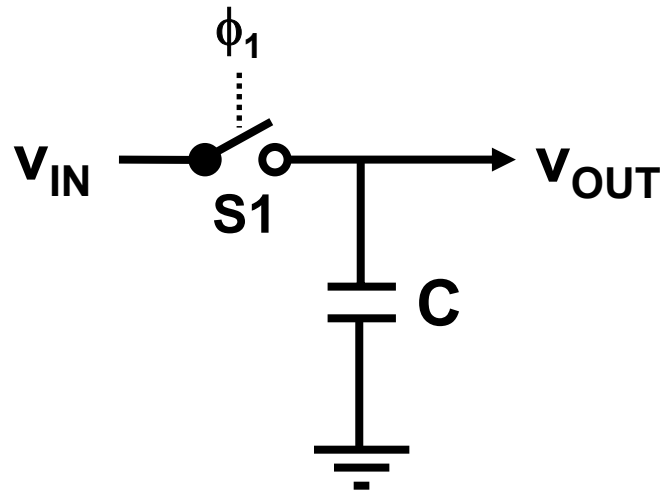
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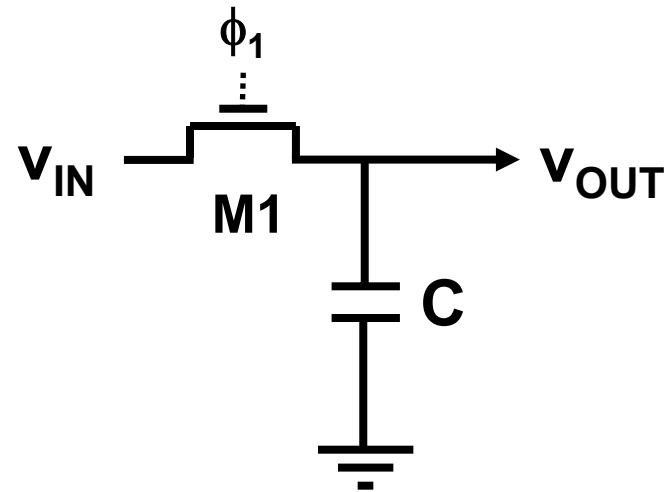
MOS Sample & Hold

Ideal Sampling

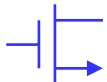


- Grab exact value of V_{in} when switch opens

Practical Sampling



- kT/C noise
- Finite $R_{sw} \rightarrow$ limited bandwidth
- $R_{sw} = f(V_{in}) \rightarrow$ distortion
- Switch charge injection
- Clock jitter

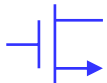


kT/C Noise

$$\frac{k_B T}{C} \leq \frac{\Delta^2}{12}$$

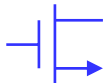
$$C \geq 12k_B T \left(\frac{2^B - 1}{V_{FS}} \right)^2$$

B [bits]	C _{min} (V _{FS} = 1V)
8	0.003 pF
12	0.8 pF
14	13 pF
16	206 pF
20	52,800 pF



MOSFET as Resistor

- “off” state
 - R_{off}
 - I_{off} ... beware of subthreshold conduction
 - Capacitive coupling
 - T-switch
- “on” state
 - Operate in triode region with V_{DS} small
 - Nonlinear
 - Threshold voltage, Body effect
 - N/P/C-MOS
 - Constant V_{GS} switch

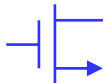
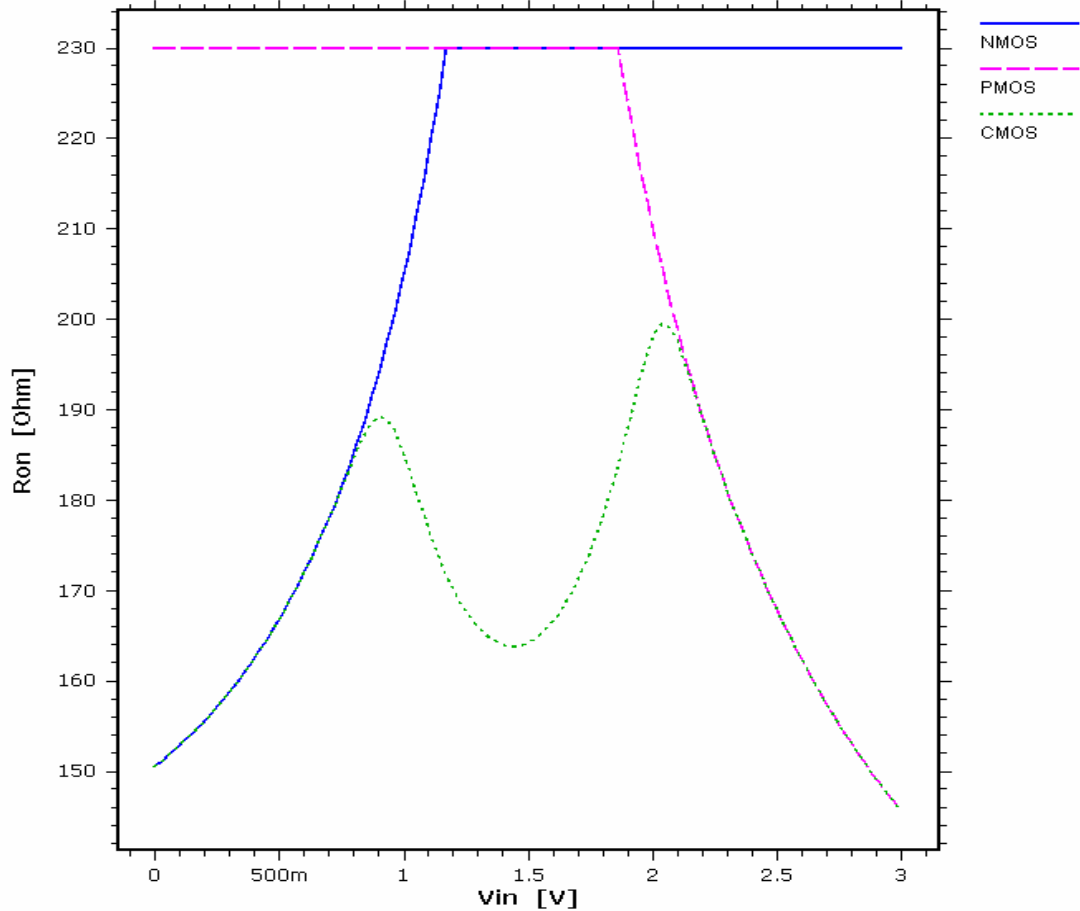
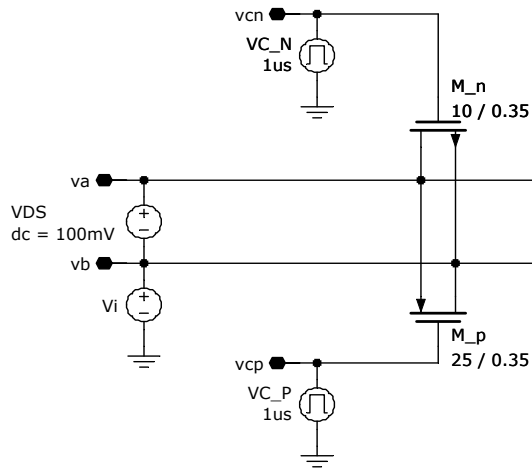


Switch On-Resistance

MOS Switch On-Resistance

Supply
VDD = 3V
VSS = 0V

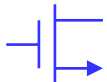
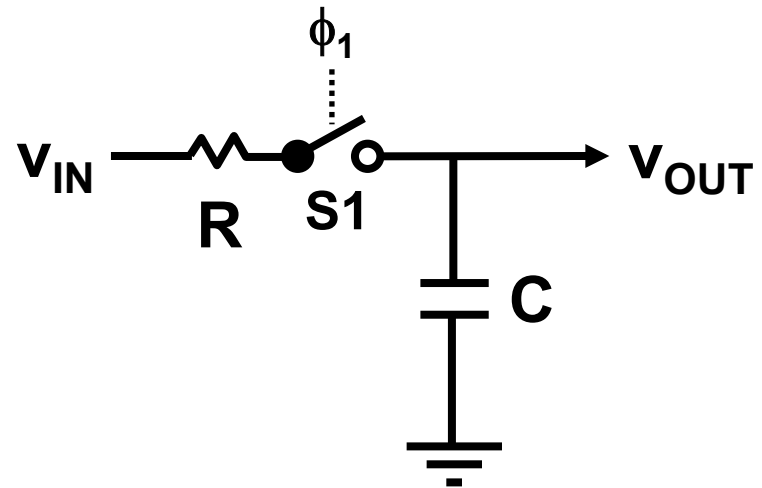
DC Analysis DC_Vi
Device Vi
sweep from 0 to 3 (100 steps)



Acquisition Bandwidth

- The resistance R of switch $S1$ turns the sampling network into a lowpass filter with risetime = $RC = \tau$
- Assuming V_{in} is constant during the sampling period and C is initially discharged (a good idea—why?):

$$v_{out}(t) = v_{in} \left(1 - e^{-t/\tau} \right)$$



Switch On-Resistance

$$v_{in} - v_{out} \left(t = \frac{1}{2f_s} \right) \ll \Delta$$

$$v_{in} e^{-1/2f_s\tau} \ll \Delta$$

Worst Case: $v_{in} = V_{FS}$

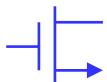
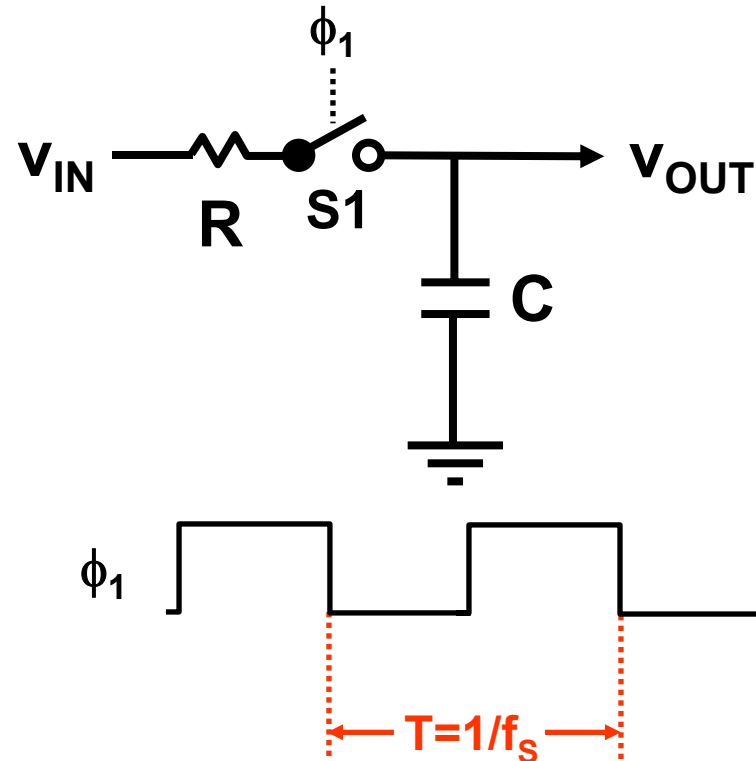
$$\tau \ll \frac{T}{2} \frac{1}{\ln(2^B - 1)} \approx \frac{0.72T}{B}$$

$$R \ll \frac{0.72}{f_s C B}$$

Example:

$$B = 14, \quad C = 13\text{pF}, \quad f_s = 100\text{MHz}$$

$$T/\tau \gg 19.4, \quad R \ll 40\Omega$$



Switch On-Resistance

$$I_{D(\text{triode})} = \mu C_{ox} \frac{W}{L} \left(V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS}$$

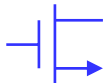
$$\frac{1}{R_{ON}} \cong \left. \frac{dI_{D(\text{triode})}}{dV_{DS}} \right|_{V_{DS} \rightarrow 0}$$

$$R_{ON} = \frac{1}{\mu C_{ox} \frac{W}{L} (V_{GS} - V_{TH})}$$

$$= \frac{1}{\mu C_{ox} \frac{W}{L} (V_{DD} - V_{TH} - v_{in})}$$

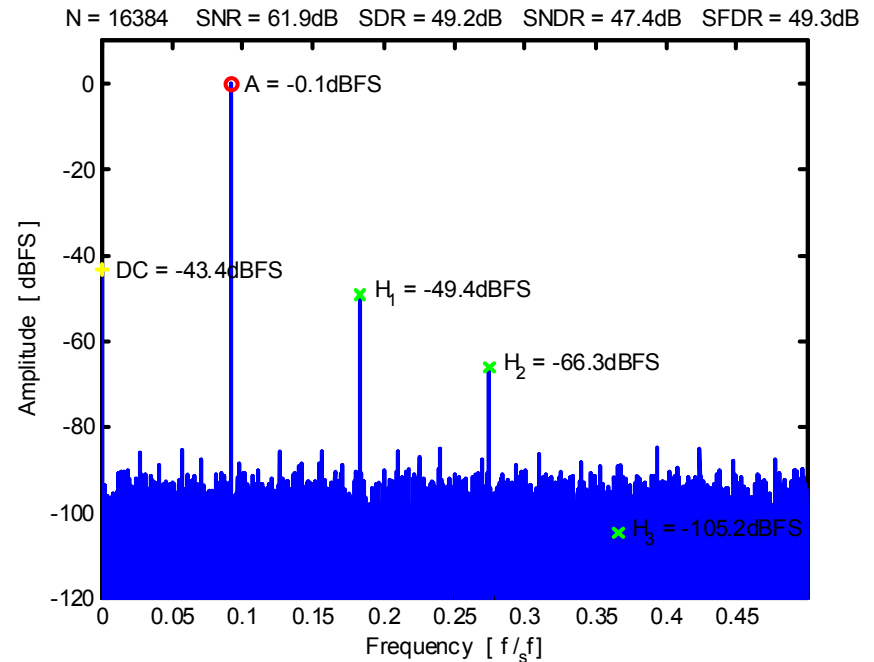
$$= \frac{R_o}{1 - \frac{v_{in}}{V_{DD} - V_{TH}}} \quad \text{with} \quad R_o = \frac{1}{\mu C_{ox} \frac{W}{L} (V_{DD} - V_{TH})}$$

$$R_{ON} = \frac{R_o}{1 - \frac{v_{in}}{V_{DD} - V_{TH}}}$$



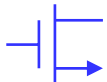
Sampling Distortion

$$v_{out} = v_{in} \left(1 - e^{-\frac{T}{2\tau} \left(1 - \frac{v_{in}}{V_{DD} - V_{TH}} \right)} \right)$$



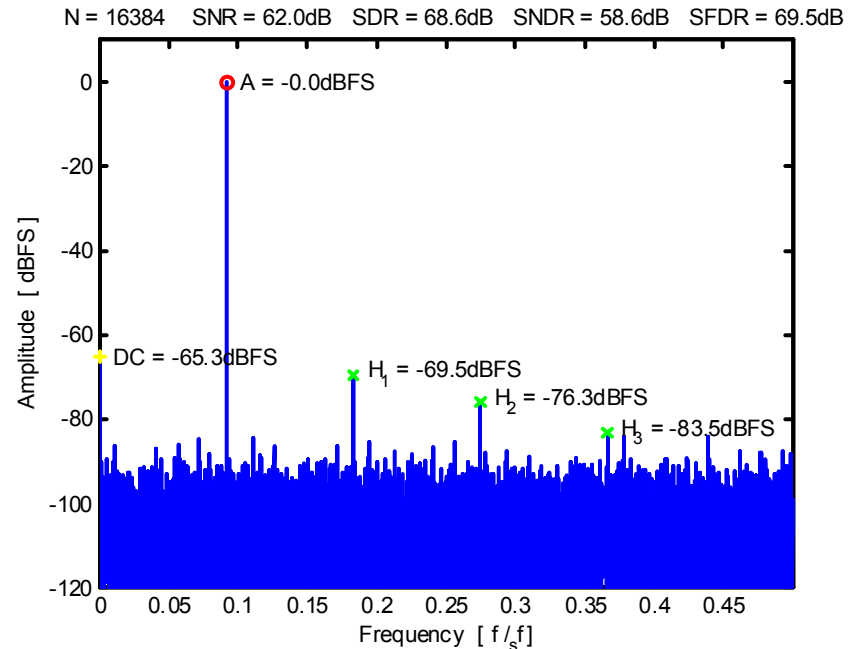
$$T/\tau = 10$$

$$V_{DD} - V_{TH} = 2V \quad V_{FS} = 1V$$



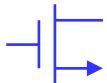
Sampling Distortion

- SFDR is very sensitive to sampling distortion
- Solutions:
 - Overdesign switches
 - increased switch charge injection
 - increased clock pwr
 - Complementary switch
 - Large V_{DD}/V_{FS}
 - increased noise
 - Constant $V_{GS} \neq f(V_{in})$
 - ...

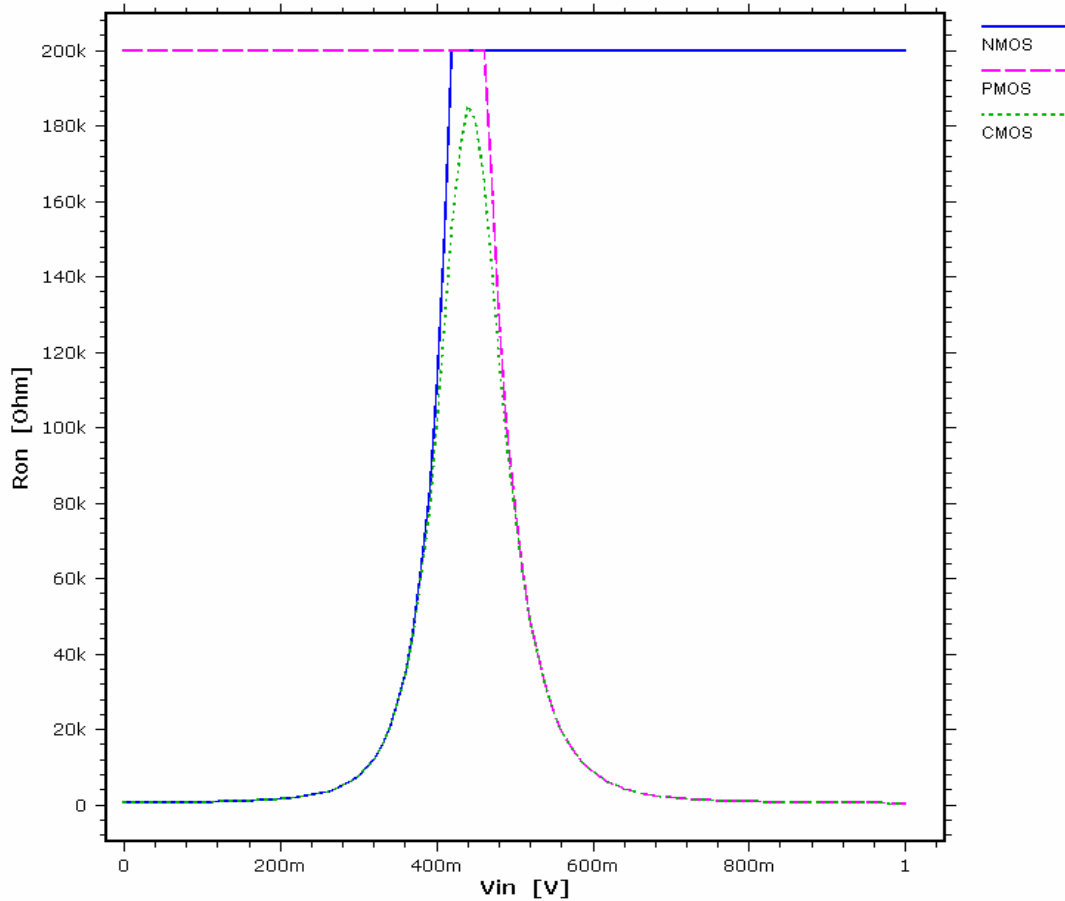


$$T/\tau = 20$$

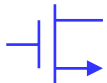
$$V_{DD} - V_{TH} = 2V \quad V_{FS} = 1V$$



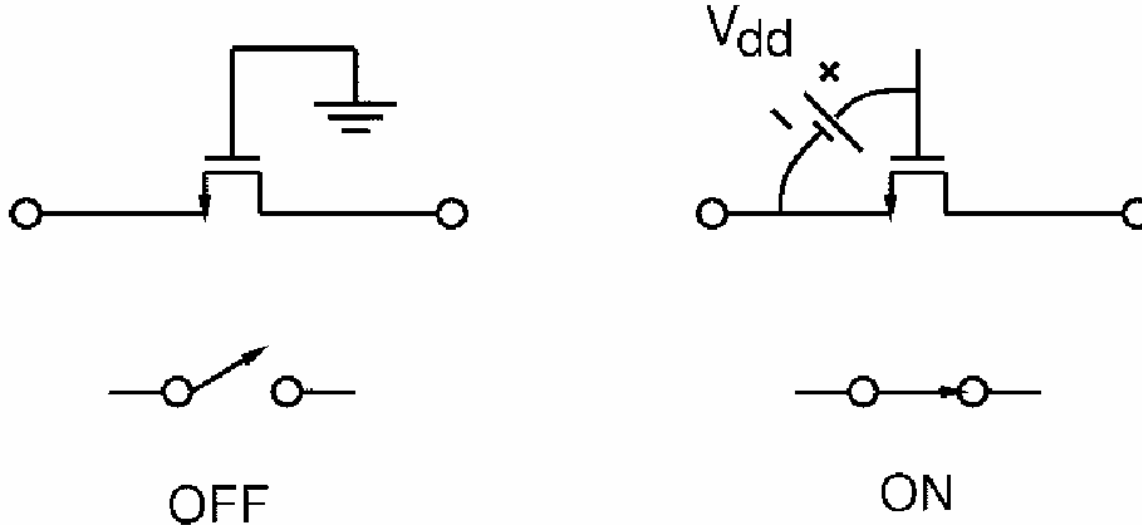
Switch On-Resistance



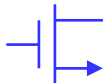
$$V_{DD} = 1V$$



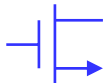
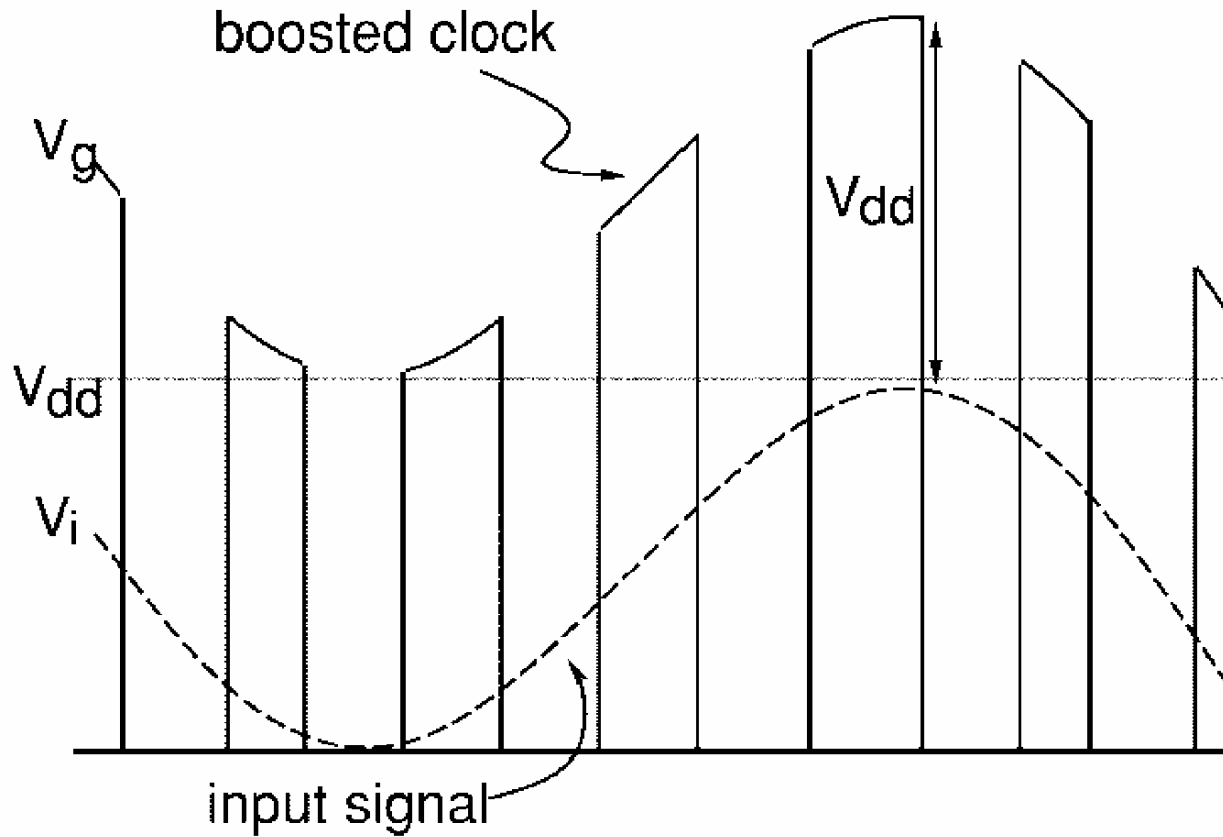
Constant V_{GS} Sampling



- Switch overdrive voltage is independent of signal
- Error from finite R_{ON} is linear (to first order)

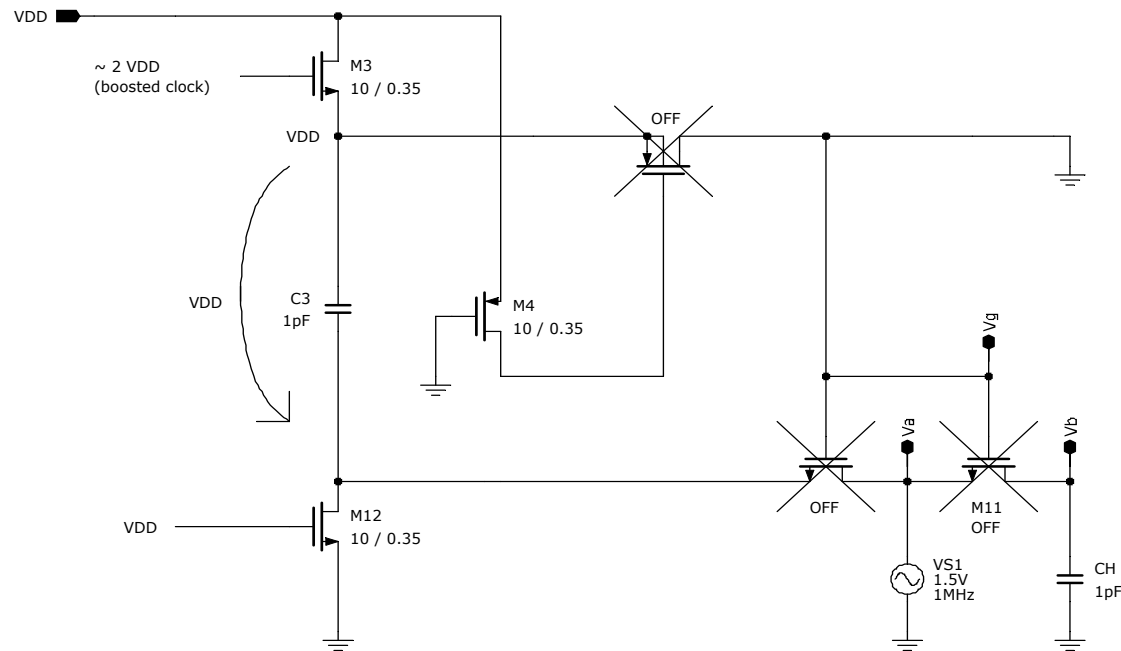


Constant V_{GS} Sampling

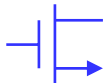


Constant V_{GS} Sampler: Φ LOW

Constant V_{GS} Switch: P is LOW

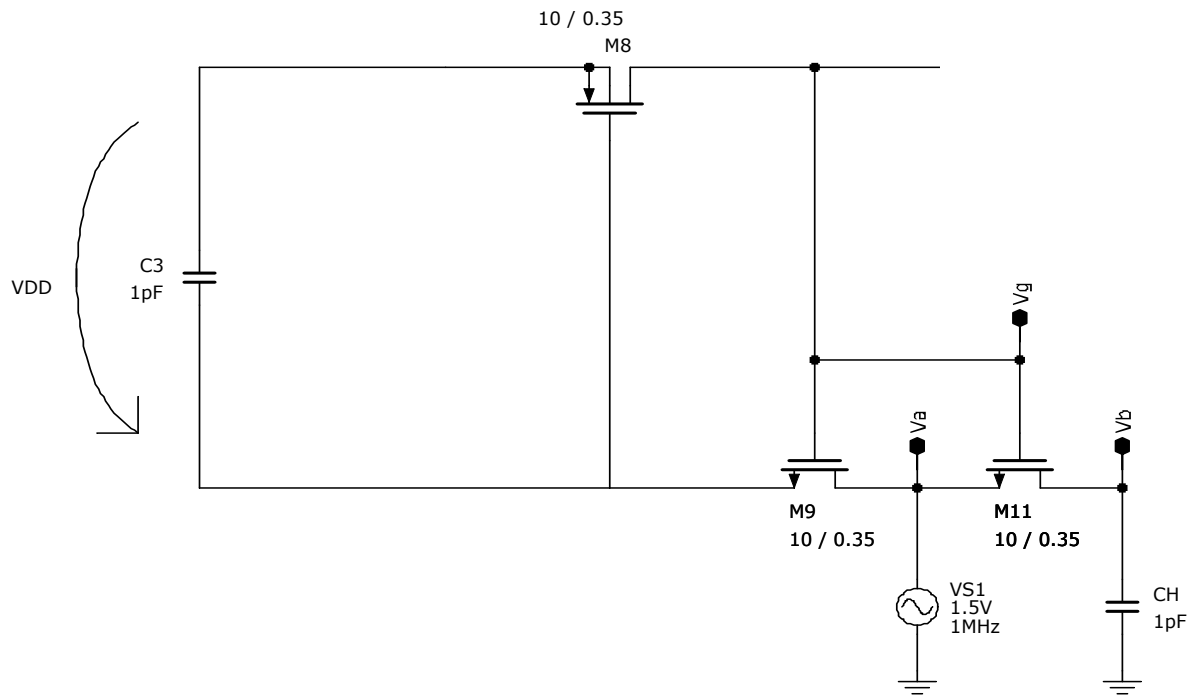


- Sampling switch M11 is OFF
- C3 charged to V_{DD}

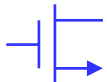


Constant V_{GS} Sampler: Φ HIGH

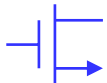
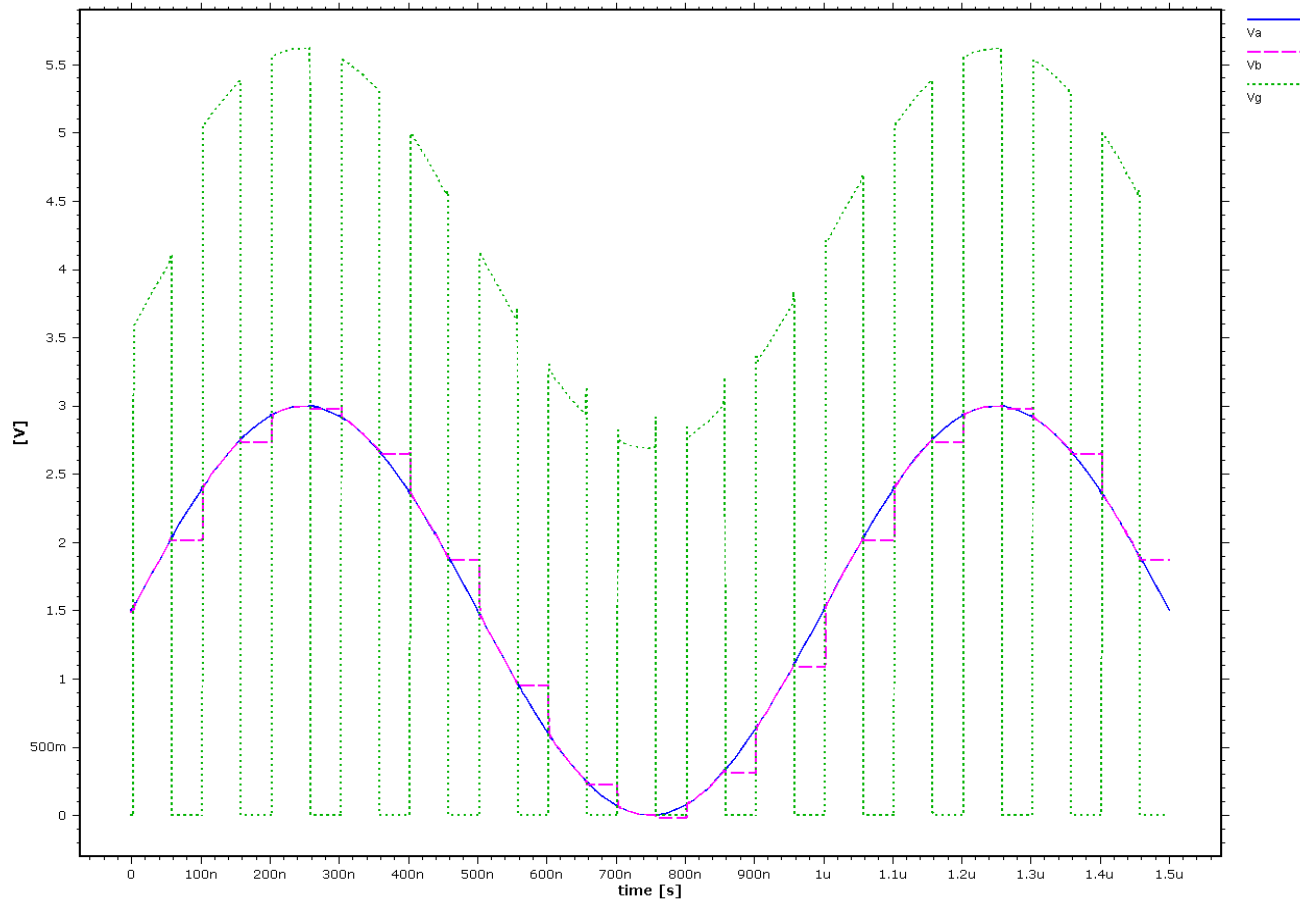
Constant V_{GS} Switch: P is HIGH



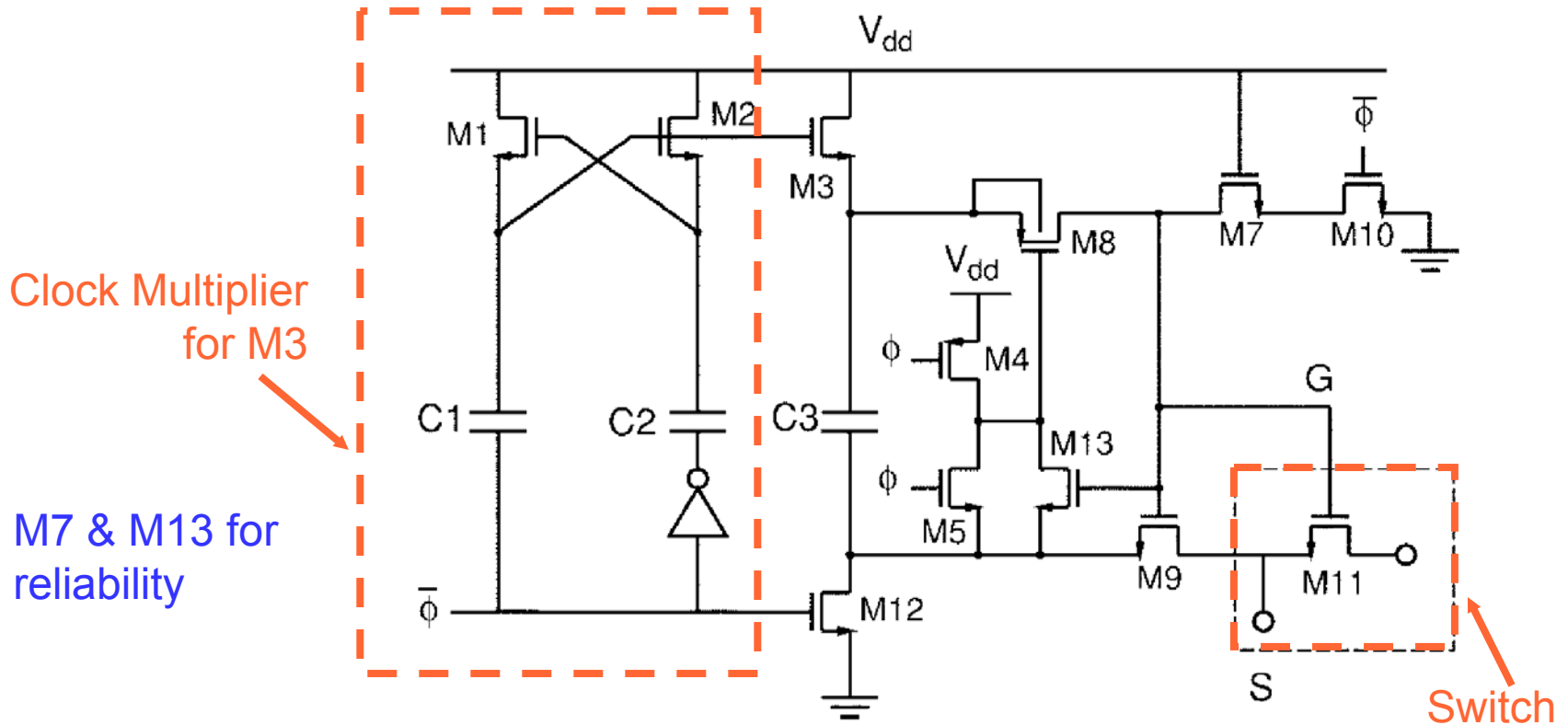
- C3 previously charged to VDD
- M8 & M9 are on: C3 across G-S of M11
- M11 on with constant $V_{GS} = VDD$



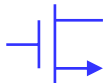
Constant V_{GS} Sampling



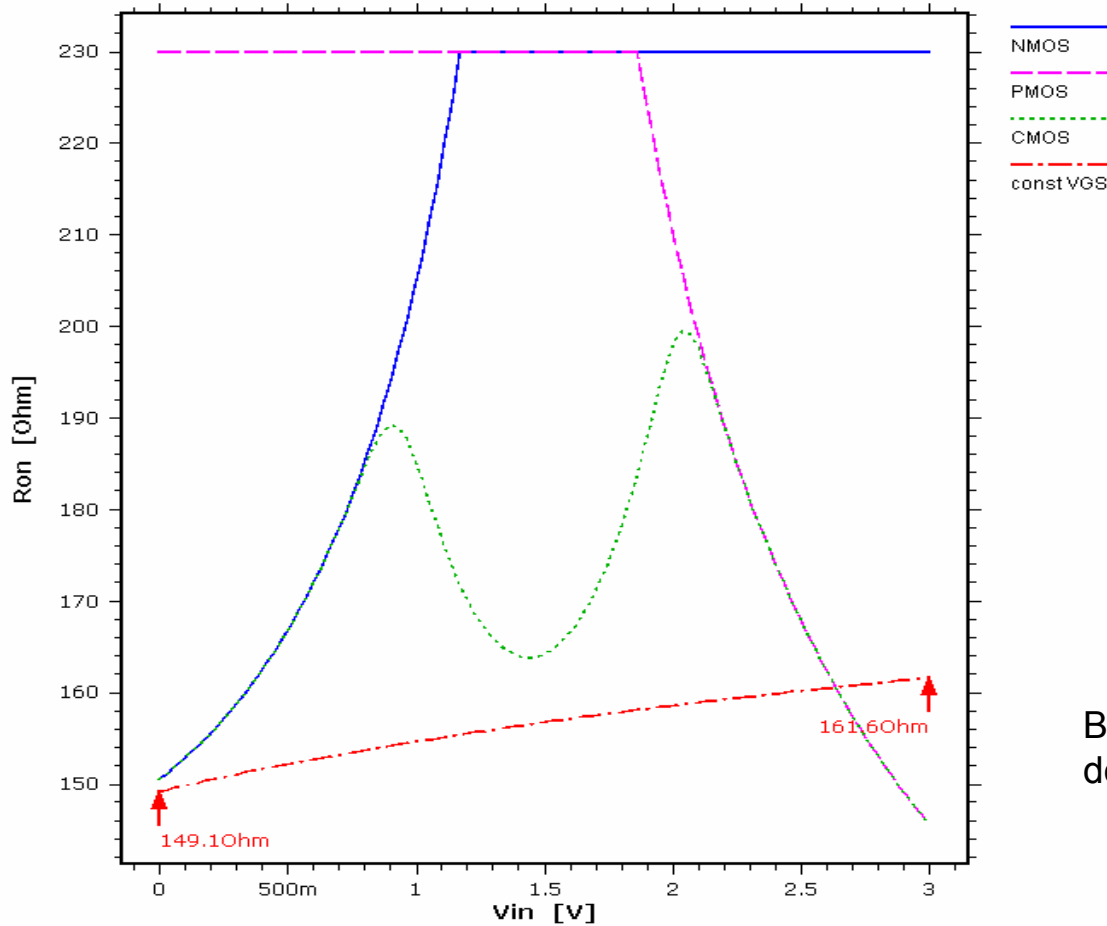
Complete Circuit



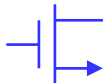
Ref: A. Abo et al, "A 1.5-V, 10-bit, 14.3-MS/s CMOS Pipeline Analog-to-Digital Converter," JSSC May 1999, pp. 599.



Switch On-Resistance

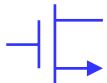


Body-effect causes residual dependence of R_{on} on V_{in}



Charge Injection

- “Extra” charge dumped onto holding capacitor
- Cause:
 - C_{ov} charge sharing
 - Channel charge
- Problems:
 - Offset
 - Distortion (error charge is function of V_{IN})
- Solutions:
 - Dummy switches
 - Bottom-plate sampling



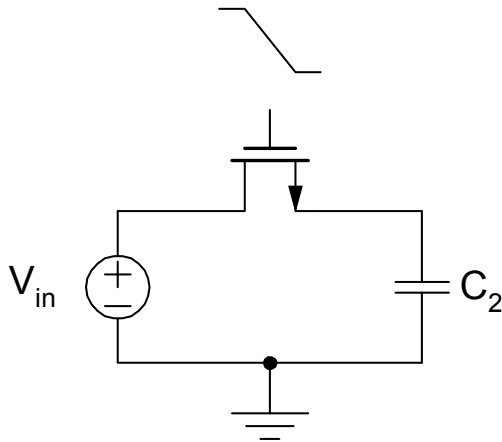
Worst-Case Error

channel charge :

$$Q_{CH} = WLC_{ox}(V_{DD} - V_{in} - V_{TH})$$

max pedestal error : $V_{in} = V_{SS}$

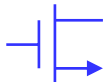
$$\Delta V = \frac{Q_{CH}}{C_2} = \frac{WLC_{ox}}{C_2}(V_{DD} - V_{SS} - V_{TH})$$



Example :

$$\Delta V = \frac{10 \times 0.35 \times 5}{1000}(3 - 0.6) = \underline{42\text{mV}}$$

- Error significant in many applications
- Worst case: not all Q_{CH} goes onto C_2
- Signal dependent: $Q_{CH}, V_{TH} \rightarrow f(V_{in})$
- Solution?



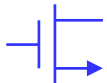
“Small Switch”

$$\tau = R_o C_2 = \frac{C_2}{\mu C_{ox} \frac{W}{L} (V_{DD} - V_{TH})}$$

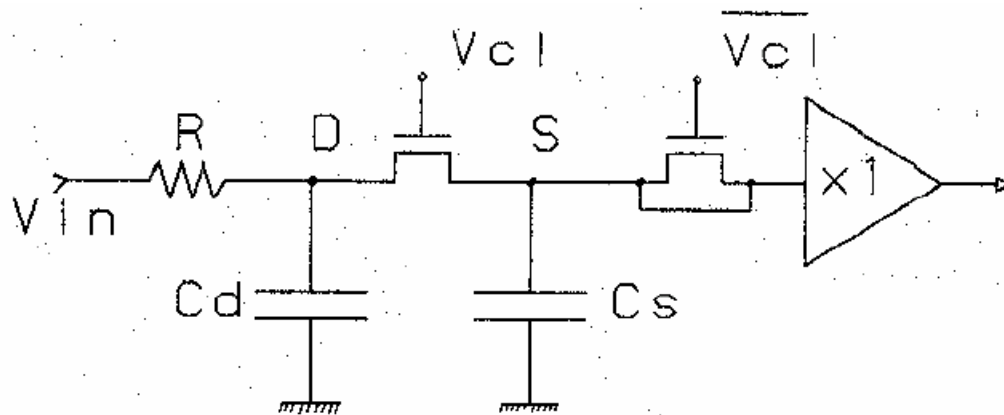
$$\Delta V = \frac{Q_{CH}}{C_2} = \frac{WLC_{ox}}{C_2} (V_{DD} - V_{SS} - V_{TH})$$

$$\begin{aligned} FOM &= \frac{C_2}{\mu C_{ox} \frac{W}{L} (V_{DD} - V_{SS} - V_{TH})} \times \frac{WLC_{ox}}{C_2} (V_{DD} - V_{SS} - V_{TH}) \\ &= \frac{L^2}{\mu} \end{aligned}$$

Reduced $\Delta V \rightarrow$ incase in τ : no optimum



Dummy Switch



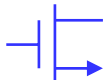
$R=6K$ $C_s=C_d=3pF$ $W/L=18\mu m/9\mu m$
 $V_{c1}=15V$; fall, risetime=20ns

- Dummy switch is half width
- Depends on equal charge split between source and drain
- Is split equal?

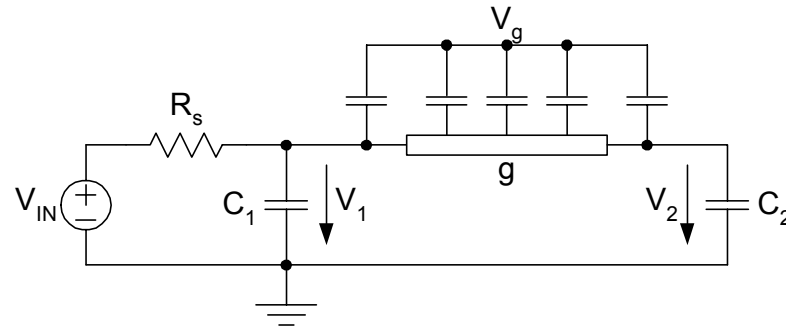
V_{in}	UNCOMPENSATED SWITCH	COMPENSATED WITH DUMMY	BALANCED SWITCH
0v	-160mV	-45mV	6mV
5v	-105mV	-30mV	1mV
10v	-40mV	-11mV	0.5mV

Ref: Bienstman et al,
 JSSC 12/1980, pp. 1051.

Eichenberger et al,
 JSSC 8/1989, pp. 1143.



Charge Injection Model



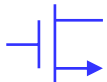
- On-state: MOSFET charge storage

- Channel: $Q_{CH} \cong WLC_{ox}(V_G - V_{IN} - V_{TH})$
- Overlap capacitance

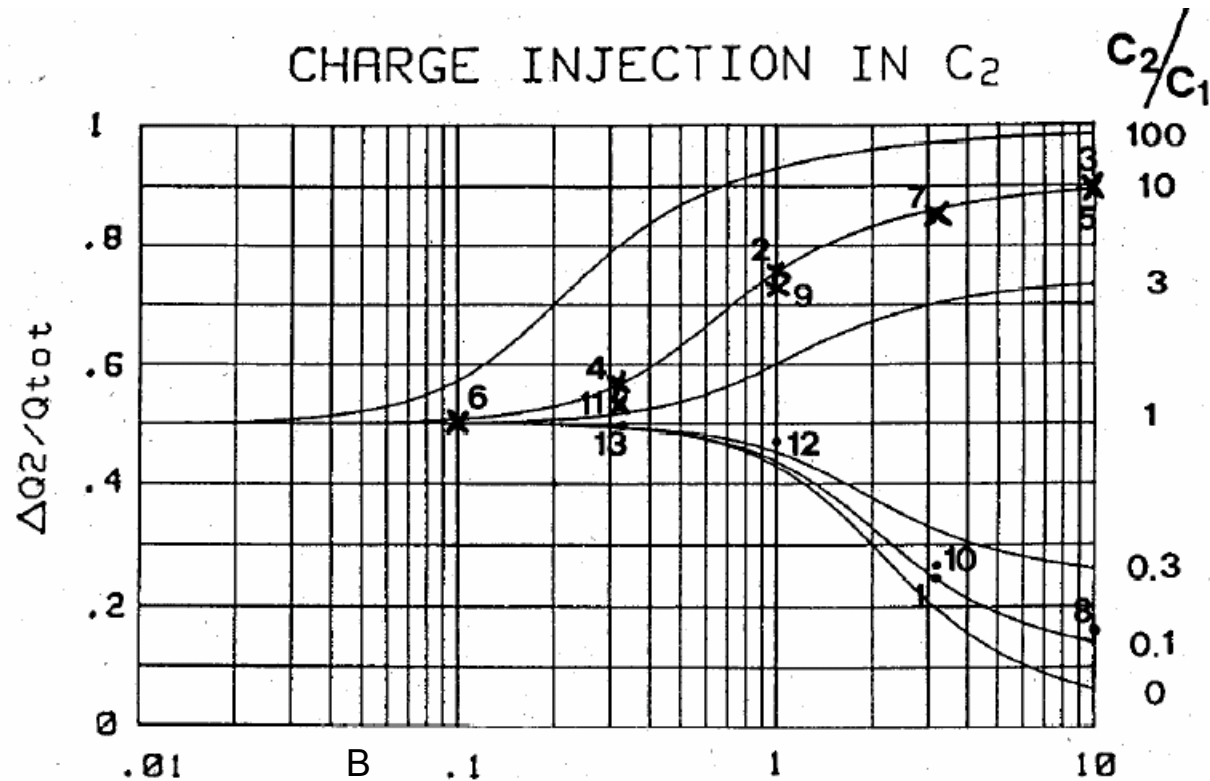
- Turn-off:

- Charge splits between C_1 and C_2
- Charge injected onto C_2 corrupts signal
- Error

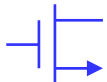
$$\frac{\Delta Q_2}{C_2 V_{IN}} = ?$$



Charge Injection Analysis



Ref: Wegmann et al, Charge injection in Analog MOS switches, IEEE J. Solid-State Circuits, pp. 1091, Dec. 1987.



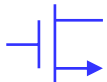
Charge Injection Analysis

Partition parameter:

$$B = \sqrt{(V_{DD} - V_{SS} - V_{TH}) t_{FALL} \frac{\mu WLC_{ox}}{L^2 C_2}}$$
$$= \sqrt{\underbrace{V_{DD} - V_{SS} - V_{TH}}_{V^*} \times \underbrace{\frac{WLC_{ox}}{C_2}} \times \underbrace{t_{FALL} \omega_T}}$$

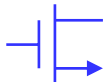
SPICE (BSIM 3v3):

XPART	Source	Drain
0 (default)	60%	40%
0.5	50%	50%
1	0%	100%



Minimizing Injection Error

1. $B \gg 1$: $t_{\text{FALL}} \gg 1/\omega_T$ and $C_1 \gg C_2$
 - All charge injected onto C_2 flows back onto C_1 during “slow” turnoff
 - Impractical: slow and uselessly large C_1
2. $C_1 = C_2$ and dummy switch (cf. Bienstmann)
 - Useless C_1 (extra area and power)
3. $B \ll 1$: requires fast switching, only approximate
4. CMOS Switch
 - Partial cancellation for “some” V_{in} (when both XTR are on)
 - Depends on (poor) matching between NMOS and PMOS
 - Beware of PM \rightarrow AM conversion (jitter):
 - Amount of injected charge depends on which switch turns off first
 - Better to depend on only on type switch turning off



Rejecting Injection Error

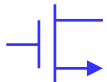
$$\Delta V = V_{OS} + f(V_{in})$$

$V_{OS} \rightarrow$ differential circuit

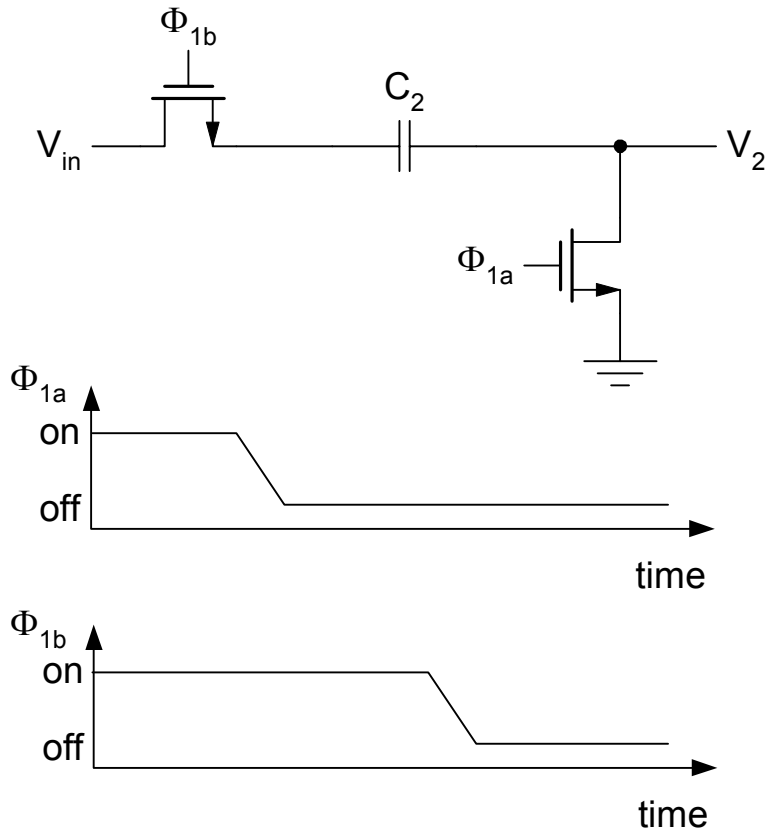
$f(V_{in}) \rightarrow$ bottom plate = const. V_{in} sampling

Refs: R. C. Yen and P. R. Gray, "An MOS switched capacitor sampling differential instrumentation amplifier," *IEEE International Solid-State Circuits Conference*, vol. XXV, pp. 82 - 83, February 1982.

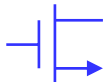
K. Lee and R. G. Meyer, "Low-distortion switched-capacitor filter design techniques," *IEEE Journal of Solid-State Circuits*, vol. 20, pp. 1103 - 1113, December 1985.



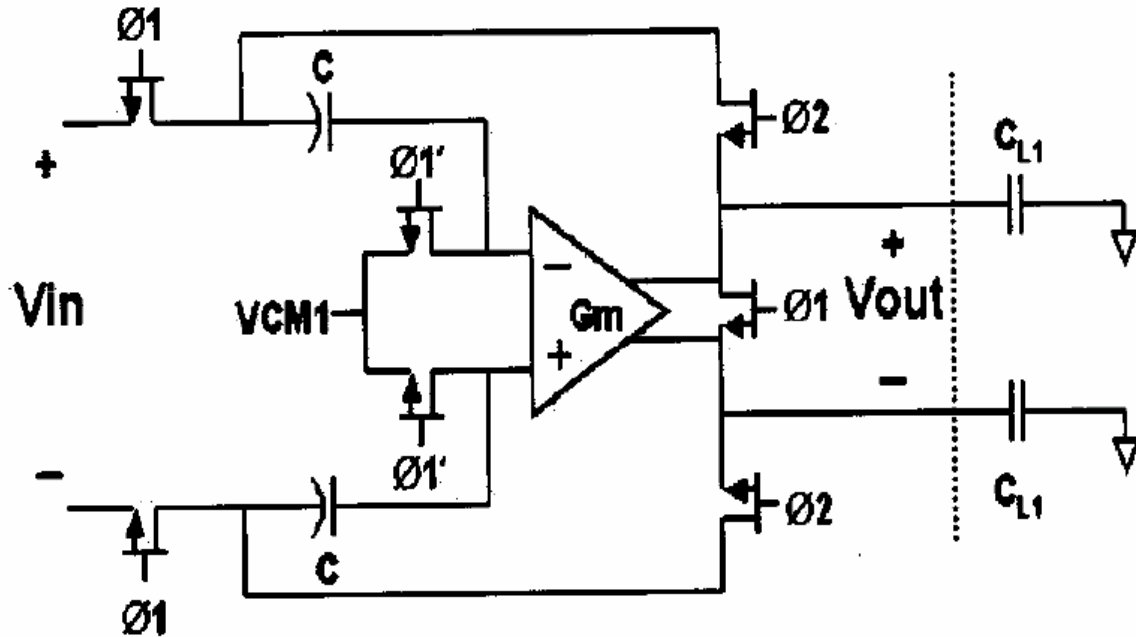
Bottom-Plate Sampling



- Switch Φ_{1a} opens first
 - Injected charge is constant, i.e. not $f(V_{in})$
 - Removed by differential implementation
- Switch Φ_{1b} opens later
 - C_2 disconnected
 - no charge injected

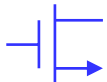


MOS T&H

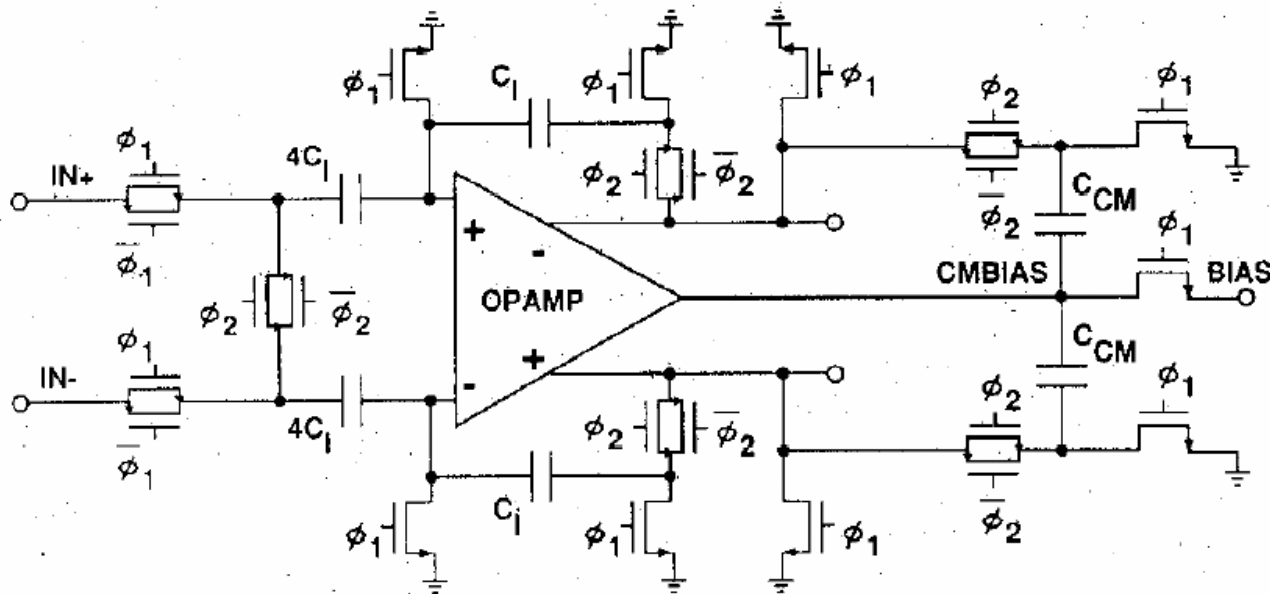


- $G = 1$
- $F_{max} = 1$
- ΔV_{icm} at input of G_m

Ref: W. Yang, D. Kelly, I. Mehr, M. T. Sayuk, and L. Singer, "A 3-V 340mW 14-b 75-Msample/s CMOS ADC with 85-dB SFDR at Nyquist input," *IEEE Journal of Solid-State Circuits*, vol. 36, pp. 1931 - 1936, December 2001.



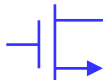
SC Gain Stage



- $G = C_s / C_f$
- $F_{\max} = 1 / (1+G)$
= 0.5 for $G=1$
- ΔV_{icm} remains on C_s

Refs: R. C. Yen and P. R. Gray, "An MOS switched capacitor sampling differential instrumentation amplifier," *IEEE International Solid-State Circuits Conference*, vol. XXV, pp. 82 - 83, February 1982.

S. H. Lewis and P. R. Gray, "A pipelined 5-Msample/s 9-bit analog-to-digital converter," *IEEE Journal of Solid-State Circuits*, vol. 22, pp. 954 - 961, December 1987.

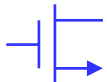


Jitter

- All of the preceding analyses assume that sampling impulses are spaced evenly in time
- Actual clocks show some distribution around the nominal value T
- The variability in T is called jitter
- Typical clocks have $>100\text{ps}+$ jitter
- Excellent (and expensive) clocks have $<1\text{ps}$ jitter

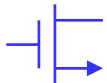
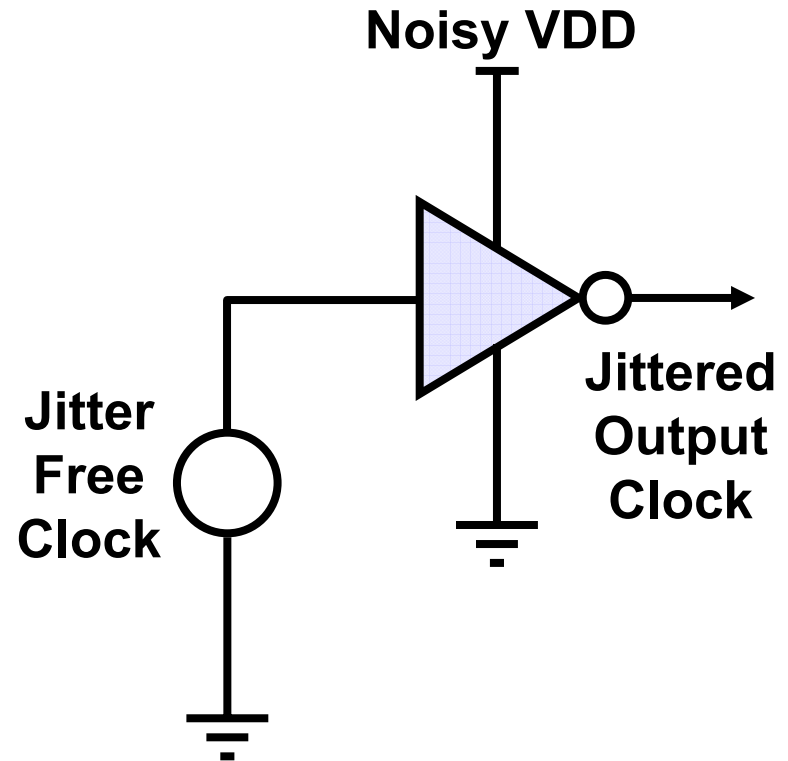
Refs: T. H. Lee, K. S. Donnelly, J. T. C. Ho, J. Zerbe, M. G. Johnson, and T. Ishikawa, "A 2.5 V CMOS delay-locked loop for 18 Mbit, 500 megabyte/s DRAM," *IEEE Journal of Solid-State Circuits*, vol. 29, pp. 1491 - 1496, December 1994.

R. Farjad-Rad, W. Dally, H. Ng, R. Senthinathan, M. E. Lee, R. Rathi, and J. Poulton, "A low-power multiplying DLL for low-jitter multigigahertz clock generation in highly integrated digital chips," *IEEE Journal of Solid-State Circuits*, vol. 37, pp. 1804 - 1812, December 2002.



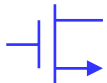
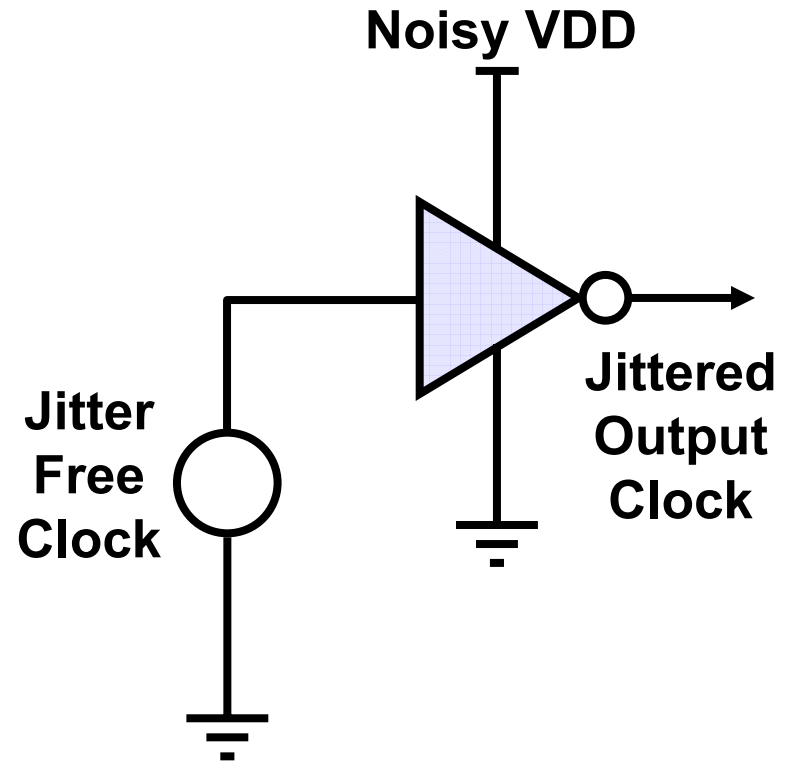
Jitter

- The dominant cause of clock jitter in most chips is power supply noise produced by unrelated activity in other parts of the chip
- The inverter symbol represents a chain of gates in the sampling clock path



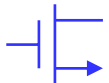
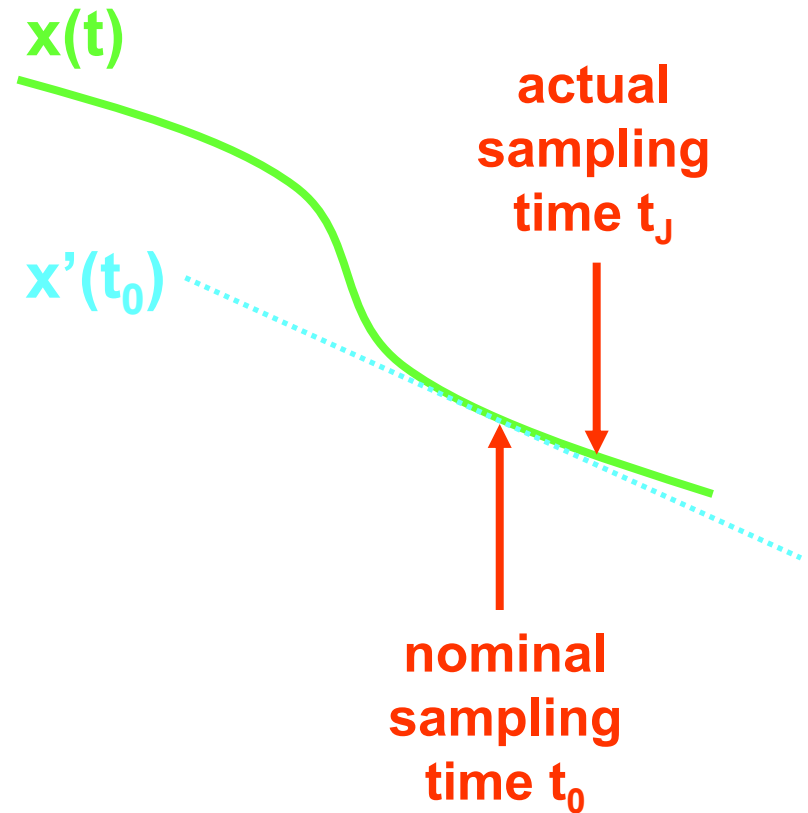
Jitter

- Let's assume the inverter delay is 100psec, and that the delay varies by 20% per volt change in V_{DD} (20psec/V)
- 200mV of power supply noise becomes 4psec of clock jitter



Jitter

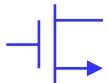
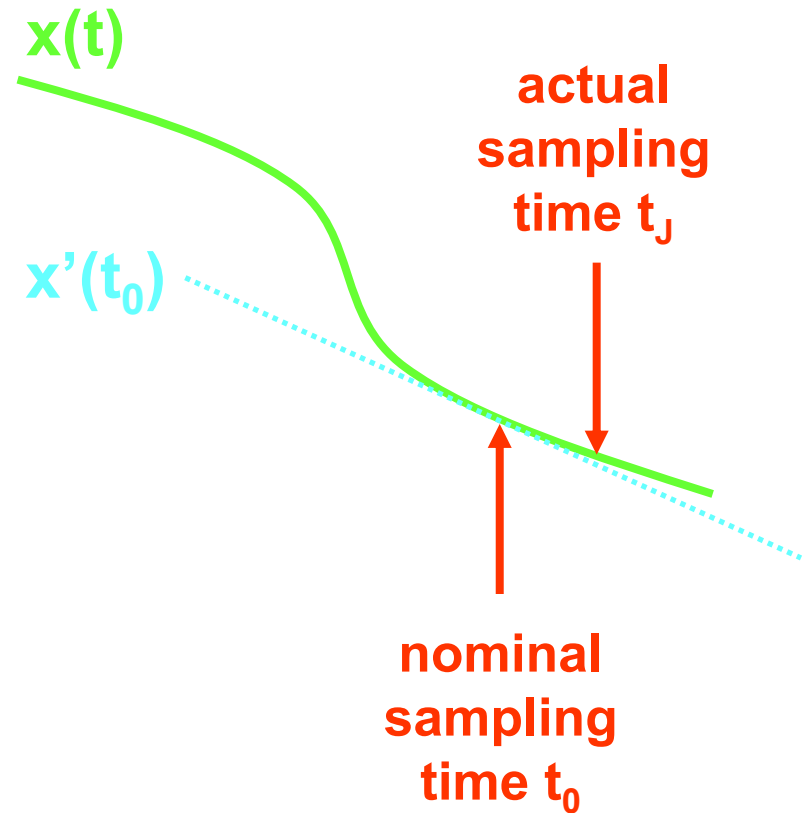
- Sampling jitter adds an error voltage proportional to the product of $(t_j - t_0)$ and the derivative of the input signal at the sampling instant
- Jitter doesn't matter when sampling dc signals



Jitter

Error voltage (1st order):

$$e = (t_j - t_o) \frac{dx(t_o)}{dt}$$



Jitter Estimate

Sinusoidal input

Amplitude: A
Frequency: f_x
Jitter: Δt

$$x(t) = A \sin(2\pi f_x t)$$

$$x'(t) = 2\pi f_x A \cos(2\pi f_x t)$$

$$|x'(t)| \leq 2\pi f_x A$$

$$|e(t)| \leq |x'(t)| \Delta t$$

Worst case

$$A = A_{FS}$$

$$f_x = f_s / 2$$

$$|e(t)| \ll \frac{\Delta}{2} \cong \frac{A_{FS}}{2^{B+1}}$$

$$\Delta t \ll \frac{1}{2^B \pi f_s}$$

B	f_s	$\Delta t \ll$ than
16	10 MHz	0.5 ps
12	100 MHz	0.8 ps
8	1000 MHz	1.2 ps

